

Title (en)

Process and device for applying an at least nearly flat supplemental product on a lateral surface of a signature

Title (de)

Verfahren und Einrichtung zum Anbringen eines zumindest annähernd flächigen Ergänzungsproduktes an einer Seitenfläche eines Druckerzeugnisses

Title (fr)

Procédé et appareil pour appliquer un produit supplémentaire au moins presque plat à une surface latérale d'une signature

Publication

EP 1588861 B1 20120229 (DE)

Application

EP 04405251 A 20040423

Priority

EP 04405251 A 20040423

Abstract (en)

[origin: EP1588861A1] A method for applying a flat product, e.g. a foil, onto a side of a folded print item looped over a transporter (13) has the relevant side raised into a horizontal position while the product is applied onto the other side. The flat product can be a self adhesive foil panel covering all or part of the side. The system can be enhanced by applying flat products onto two sides at once. The system can also be enhanced by applying the product to either side of a page.

IPC 8 full level

B42C 1/00 (2006.01); **B42C 1/10** (2006.01); **B44C 1/00** (2006.01); **B65H 5/30** (2006.01); **B65H 5/32** (2006.01); **B65H 37/04** (2006.01); **B65H 39/06** (2006.01)

CPC (source: EP US)

B42C 1/10 (2013.01 - EP US); **B65H 5/30** (2013.01 - EP US); **B65H 5/32** (2013.01 - EP US); **B65H 39/06** (2013.01 - EP US); **Y10T 156/10** (2015.01 - EP US); **Y10T 156/17** (2015.01 - EP US); **Y10T 156/1705** (2015.01 - EP US); **Y10T 156/1744** (2015.01 - EP US); **Y10T 156/1763** (2015.01 - EP US); **Y10T 156/1771** (2015.01 - EP US); **Y10T 156/1773** (2015.01 - EP US); **Y10T 156/1776** (2015.01 - EP US); **Y10T 156/1785** (2015.01 - EP US); **Y10T 156/1798** (2015.01 - EP US)

Designated contracting state (EPC)

CH DE FR GB IT LI

DOCDB simple family (publication)

EP 1588861 A1 20051026; **EP 1588861 B1 20120229**; JP 2005306609 A 20051104; JP 5054286 B2 20121024; US 2005241753 A1 20051103; US 2009038733 A1 20090212; US 7438107 B2 20081021; US 8162019 B2 20120424

DOCDB simple family (application)

EP 04405251 A 20040423; JP 2005077018 A 20050317; US 11106805 A 20050421; US 28331608 A 20080911